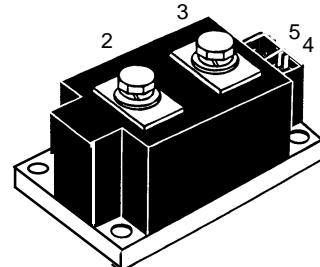
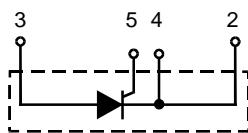


High Power Thyristor Modules

I_{TRMS} = 880 A
I_{T(AV)M} = 560 A
V_{RRM} = 1200-1800 V

V _{RSM} V _{DSM} V	V _{RRM} V _{DRM} V	Type
1300	1200	MCO 500-12io1
1500	1400	MCO 500-14io1
1700	1600	MCO 500-16io1
1900	1800	MCO 500-18io1



Symbol	Test Conditions	Maximum Ratings		
I _{TRMS}	T _{VJ} = T _{VJM}	880	A	
I _{T(AV)M}	T _C = 85°C; 180° sine	560	A	
I _{TSM}	T _{VJ} = 45°C V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	17000 16000	A A
	T _{VJ} = T _{VJM} V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	13000 14400	A A
I ² t	T _{VJ} = 45°C V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	1445000 1062000	A ² s A ² s
	T _{VJ} = T _{VJM} V _R = 0	t = 10 ms (50 Hz) t = 8.3 ms (60 Hz)	845000 813000	A ² s A ² s
(di/dt) _{cr}	T _{VJ} = T _{VJM} f = 50 Hz, t _p = 200 μs V _D = 2/3 V _{DRM}	repetitive, I _T = 960 A	100	A/μs
	I _G = 1 A, non repetitive, I _T = I _{T(AV)M} di _G /dt = 1 A/μs		500	A/μs
(dv/dt) _{cr}	T _{VJ} = T _{VJM} ; V _{DR} = 2/3 V _{DRM} R _{GR} = ∞; method 1 (linear voltage rise)		1000	V/μs
P _{GM}	T _{VJ} = T _{VJM}	t _p = 30 μs	120	W
	I _T = I _{T(AV)M}	t _p = 500 μs	60	W
P _{GAV}			30	W
V _{RGM}			10	V
T _{VJ}			-40...140	°C
T _{VJM}			140	°C
T _{stg}			-40...125	°C
V _{ISOL}	50/60 Hz, RMS	t = 1 min	3000	V~
	I _{ISOL} ≤ 1 mA	t = 1 s	3600	V~
M _d	Mounting torque (M6)		4.5-7/40-62	Nm/lb.in.
	Terminal connection torque (M8)		11-13/97-115	Nm/lb.in.
Weight	Typical including screws		650	g

Data according to IEC 60747 refer to a single thyristor/diode unless otherwise stated.
 IXYS reserves the right to change limits, test conditions and dimensions

Features

- International standard package
- Direct copper bonded Al₂O₃-ceramic with copper base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered E 72873
- Keyed gate/cathode twin pins

Applications

- Motor control, softstarter
- Power converter
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Solid state switches

Advantages

- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Symbol	Test Conditions	Characteristic Values	
I_{RRM}	$T_{VJ} = T_{VJM}; V_R = V_{RRM}$	40	mA
V_T	$I_T = 1200 \text{ A}; T_{VJ} = 25^\circ\text{C}$	1.3	V
V_{TO}	For power-loss calculations only ($T_{VJ} = T_{VJM}$)	0.8	V
r_T		0.38	$\text{m}\Omega$
V_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	2 3	V
I_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	300 400	mA
V_{GD}	$T_{VJ} = T_{VJM}; V_D = 2/3 V_{DRM}$	0.25	V
I_{GD}	$T_{VJ} = T_{VJM}; V_D = 2/3 V_{DRM}$	10	mA
I_L	$T_{VJ} = 25^\circ\text{C}; V_D = 6 \text{ V}; t_p = 30 \mu\text{s}$ $di_G/dt = 1 \text{ A}/\mu\text{s}; I_G = 1 \text{ A}$	400	mA
I_H	$T_{VJ} = 25^\circ\text{C}; V_D = 6 \text{ V}; R_{GK} = \infty$	300	mA
t_{gd}	$T_{VJ} = 25^\circ\text{C}; V_D = 1/2 V_{DRM}$ $di_G/dt = 1 \text{ A}/\mu\text{s}; I_G = 1 \text{ A}$	2	μs
t_q	$T_{VJ} = T_{VJM}; V_R = 100 \text{ V}; V_D = 2/3 V_{DRM}; t_p = 200 \mu\text{s}$ $dv/dt = 50 \text{ V}/\mu\text{s}; I_T = 500 \text{ A}; -di/dt = 10 \text{ A}/\mu\text{s}$	typ. 350	μs
R_{thJC}	DC current	0.072	K/W
R_{thJK}	DC current	0.096	K/W
d_s	Creeping distance on surface	12.7	mm
d_A	Creepage distance in air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

Optional accessories for modules

Keyed Gate/Cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red

Type **ZY 180 L** (L = Left for pin pair 4/5) { UL 758, style 1385,
CSA class 5851, guide 460-1-1

Dimensions in mm (1 mm = 0.0394")

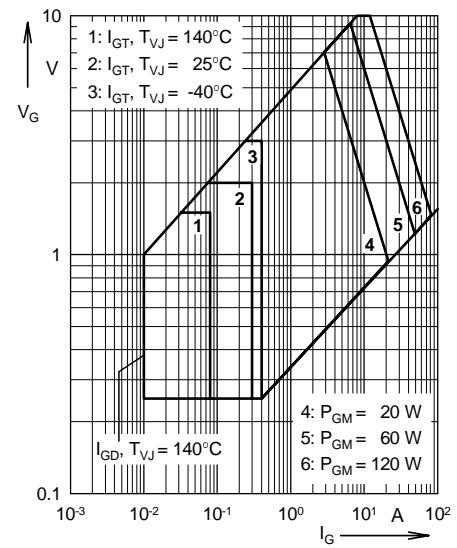
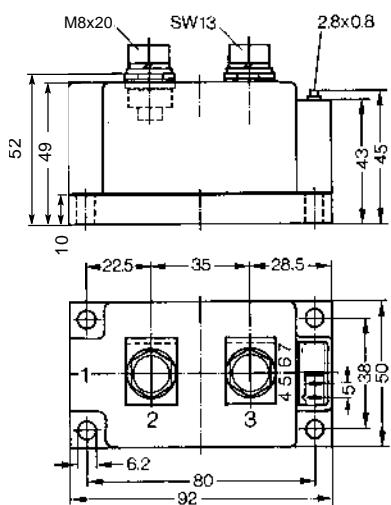


Fig. 1 Gate trigger characteristics

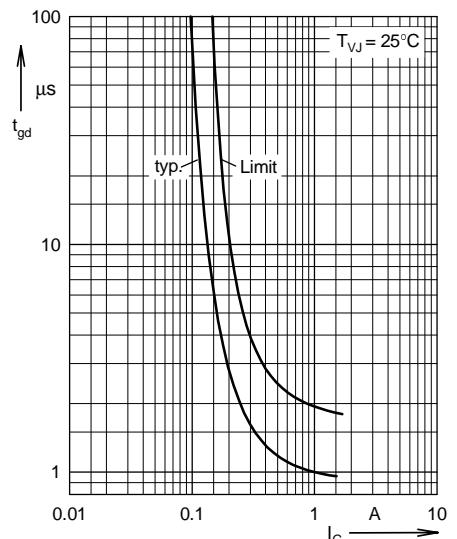


Fig. 2 Gate trigger delay time

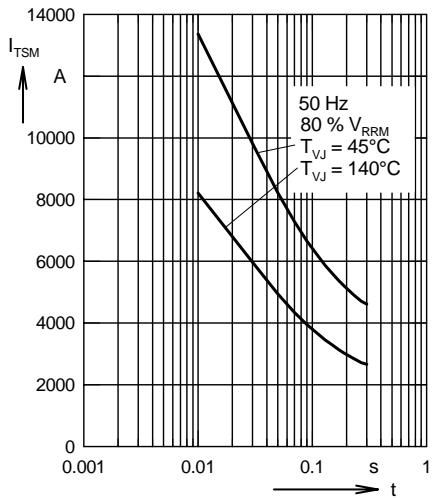


Fig. 3 Surge overload current
 I_{TSM}, I_{FSM} : Crest value, t : duration

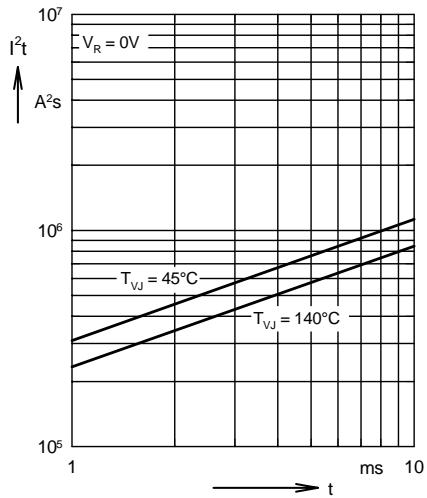


Fig. 4 $\int i^2 dt$ versus time (1-10 ms)

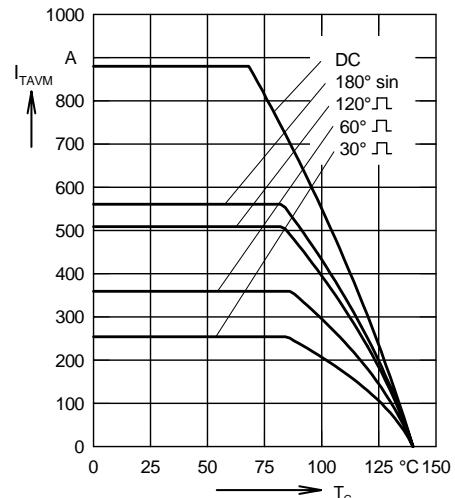


Fig. 5 Maximum forward current at case temperature

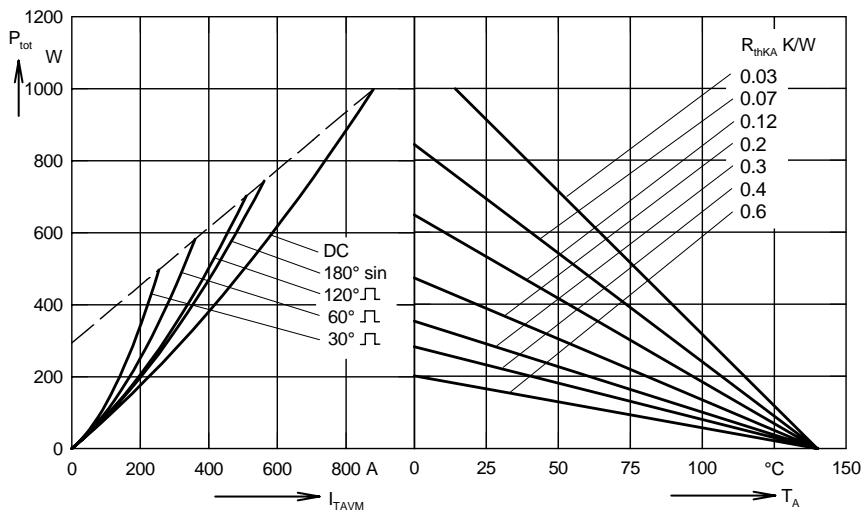


Fig. 6 Power dissipation versus on-state current and ambient temperature

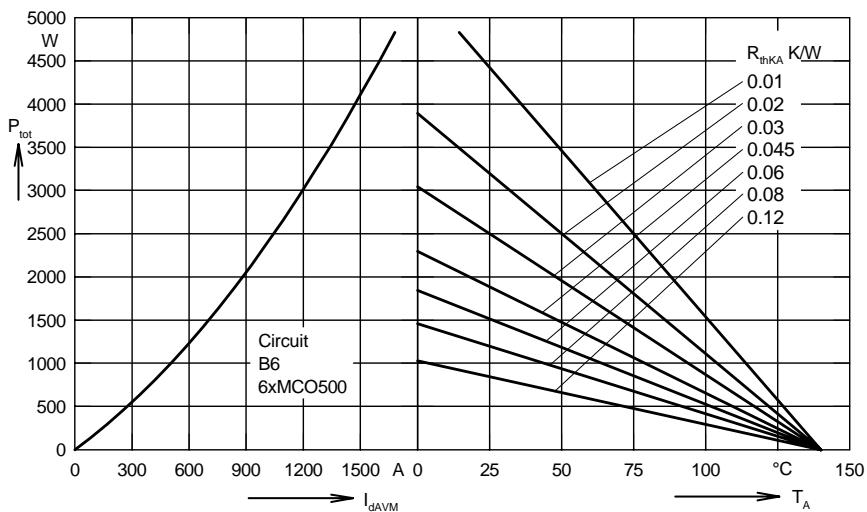


Fig. 7 Three phase rectifier bridge:
Power dissipation versus direct output current and ambient temperature

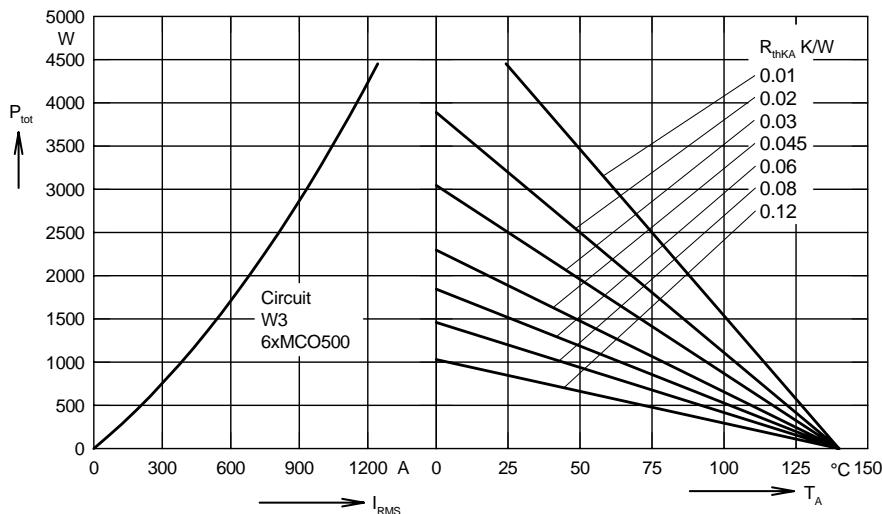


Fig. 8 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

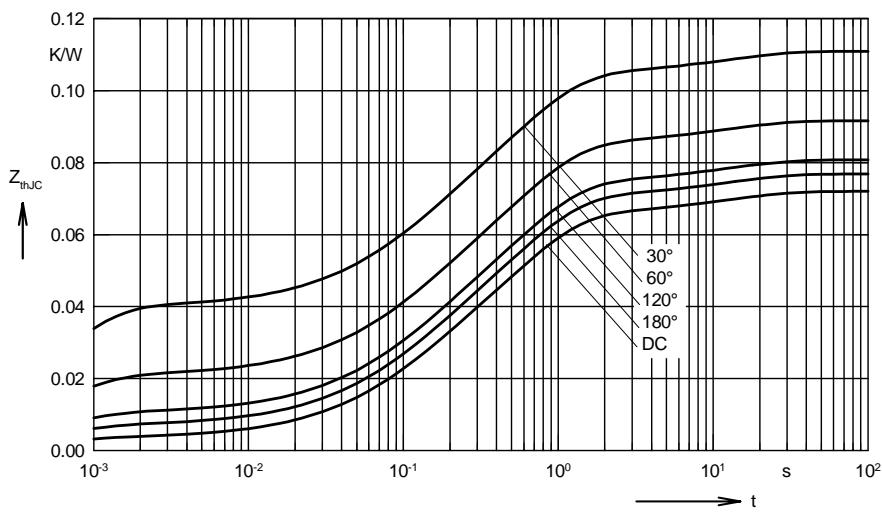


Fig. 9 Transient thermal impedance
junction to case (per thyristor)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.072
180°	0.0768
120°	0.081
60°	0.092
30°	0.111

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0054
2	0.0186	0.098
3	0.0432	0.54
4	0.0067	12

Fig.10 Transient thermal impedance
junction to heatsink (per thyristor)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.096
180°	0.1
120°	0.105
60°	0.116
30°	0.135

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0054
2	0.0186	0.098
3	0.0432	0.54
4	0.0067	12
5	0.024	12